

**VERSION WITH MARKINGS TO SHOW CHANGES**

**In The Specification**

Section beginning on page 1, line 1.

**Cross Reference to Related Applications**

This is a continuation of Application Serial No. 08/910,500 filed August 4, 1997, now U.S. Patent No. 6,232,213, which is a continuation of Application Serial No. 08/436,522 filed May 8, 1995, now U.S. Patent No. 5,677,566.

**In The Claims**

19. (amended twice) A semiconductor chip package, comprising:  
a semiconductor chip;  
conductive leads electrically connected to and extending over a surface of the chip;  
a continuous body of encapsulating material covering at least a portion of the chip and fully encapsulating the conductive leads; and  
electrodes each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.

23. (amended once) A semiconductor chip package, comprising:  
a semiconductor chip;  
conductive leads electrically connected to and extending over a surface of the chip;  
a continuous body of encapsulating material covering at least a portion of the chip and at least a portion of the conductive leads; and  
solder balls each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.

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24.(amended once) A semiconductor chip package, comprising:  
a semiconductor chip having bond pads aligned along a surface of the chip;  
insulating material on the surface of the chip, the insulating material having holes  
therein to enable electrical connection to the bond pads;  
conductive leads attached to the insulating material, each lead electrically  
connected to and extending over the bond pads;  
a continuous body of encapsulating material covering at least a portion of the  
chip and at least a portion of the conductive leads; and  
solder balls each having a first portion disposed in the encapsulating material  
and contacting a conductive lead and a second portion protruding from the  
encapsulating material.